



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

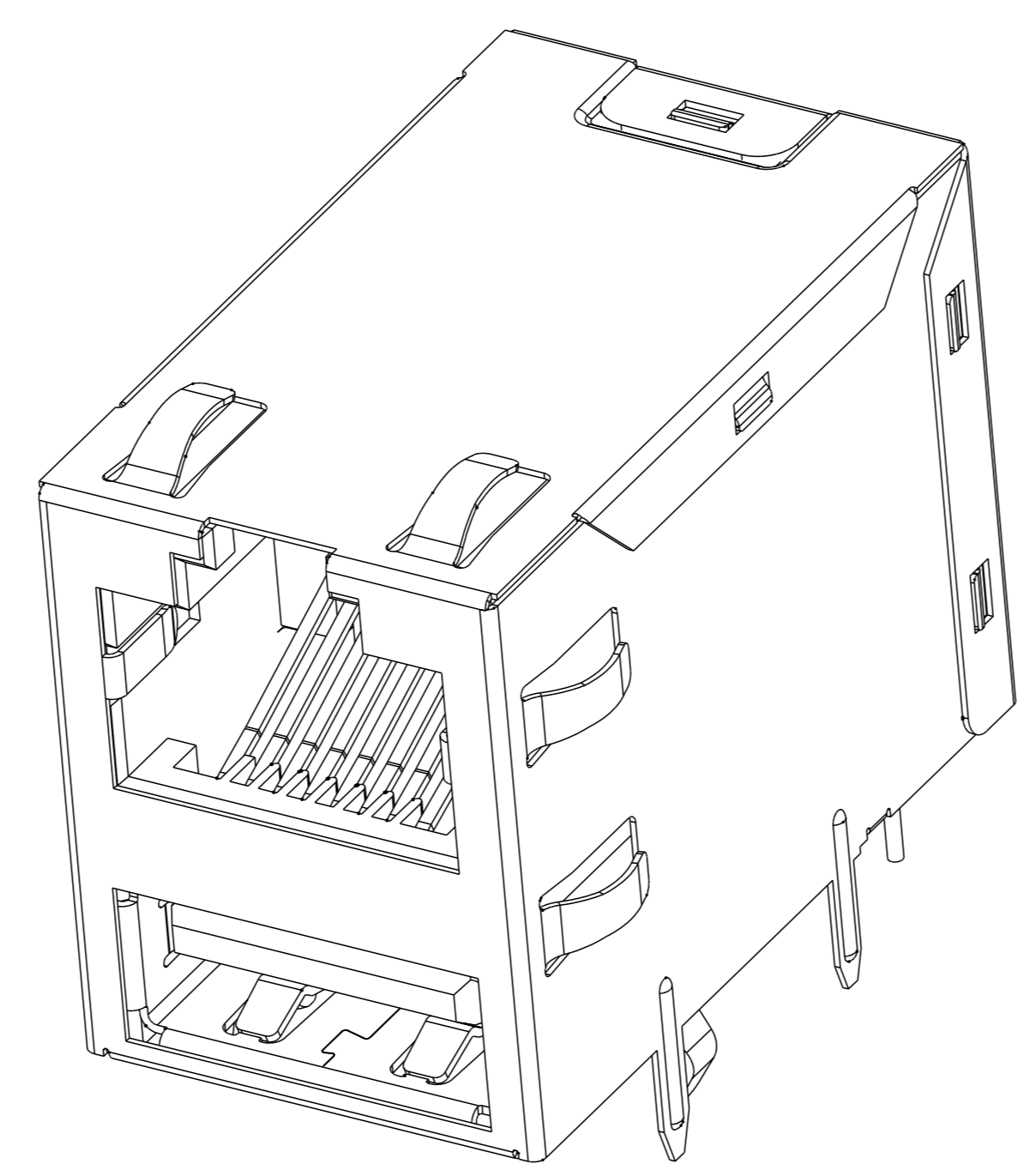
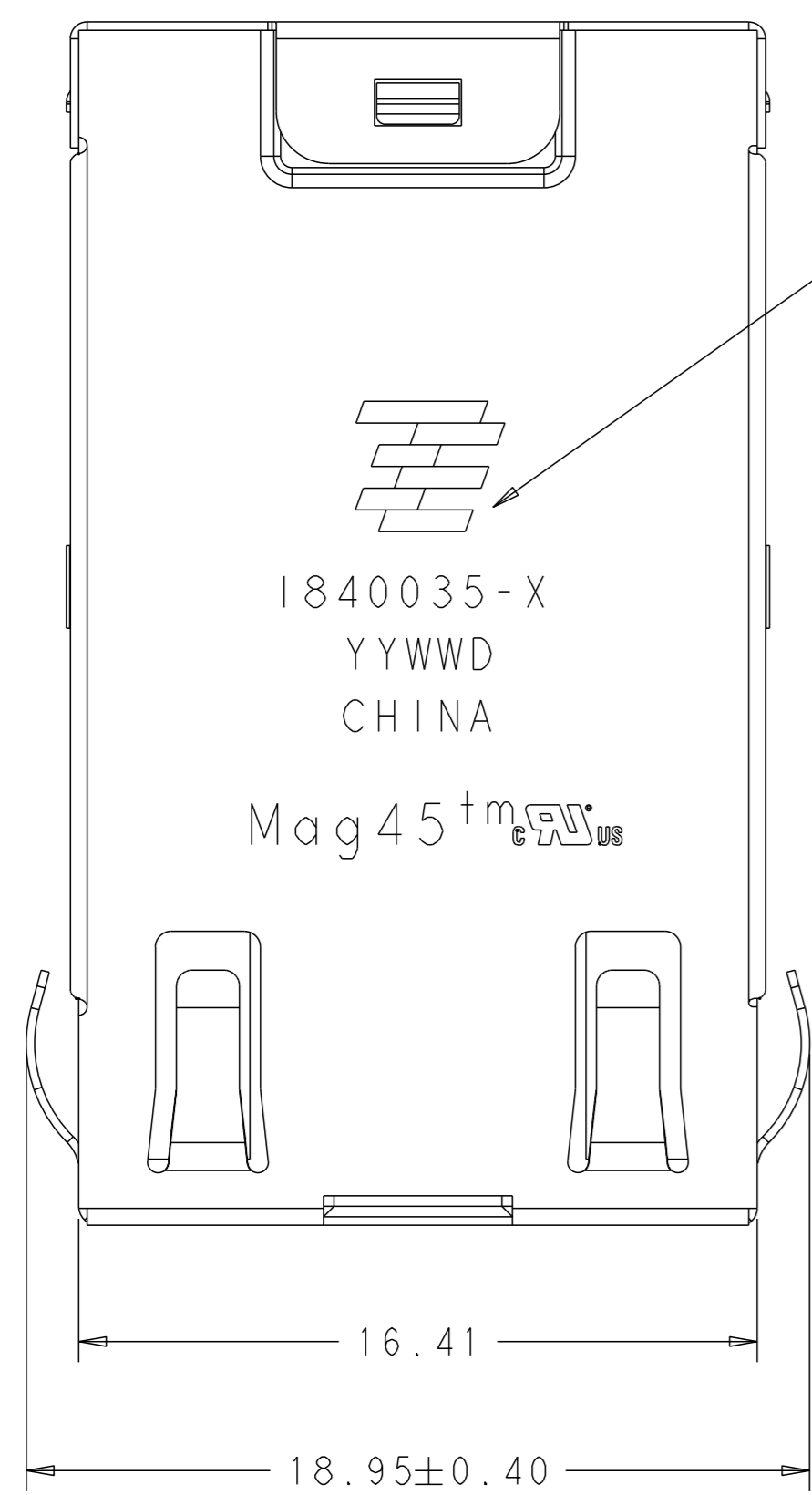
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



REVISIONS				
#	LY#	DESCRIPTION	DATE	OWN APVD
C		ECO-16-005052	01APR2016	LL SH



1. RJ45 MATERIALS

HOUSING: THERMOPLASTIC, BLACK, FLAMMABILITY RATED UL 94V-0  
 SHIELD : BRASS, 0.2 mm THICK, PREPLATED WITH MIN 0.76 um SEMI-BRIGHT NICKEL, POST DIPPED WITH 2.54 um MIN SAC SOLDER AT GROUND PINS.  
 CONTACT: PHOSPHOR BRONZE, WITH 1.27 um MIN OVERALL NICKEL UNDERPLATE AND SELECTIVE 1.27 um MIN GOLD PLATING AT MATING INTERFACE  
 SOLDER TAIL: COPPER STEEL, PLATED WITH 2.54 um MIN MATTE TIN

USB MATERIALS:

HOUSING: THERMOPLASTIC, FLAMMABILITY RATED UL94V-0  
 CONTACT: COPPER ALLOY WITH 0.76 MIN GOLD PLATING OVER 1.27 um MIN OVERALL NICKEL UNDERPLATE  
 SHELL : COPPER ALLOY, PREPLATED WITH MIN 0.76 um SEMI-BRIGHT NICKEL, 2.54 um TIN PLATED

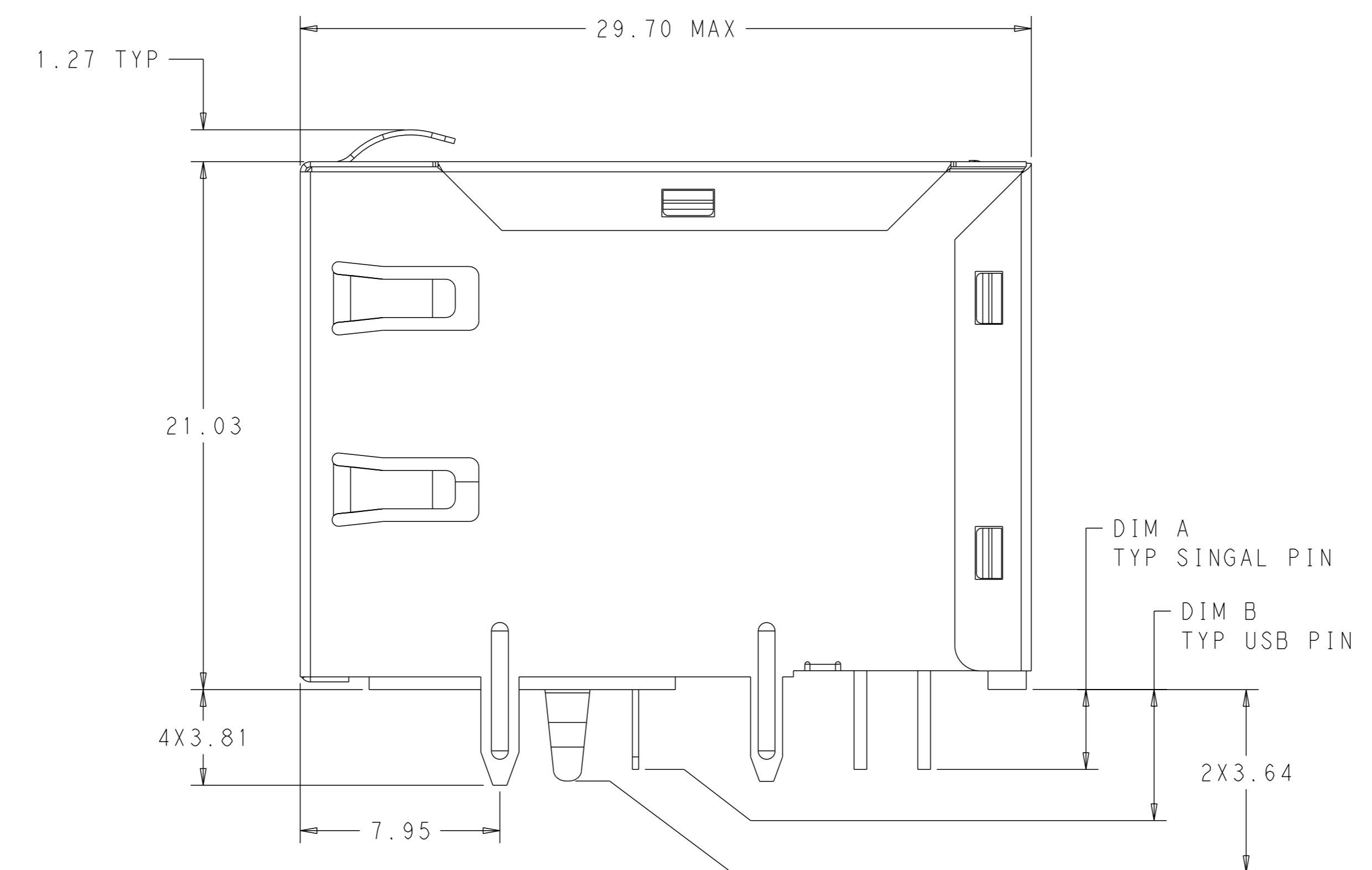
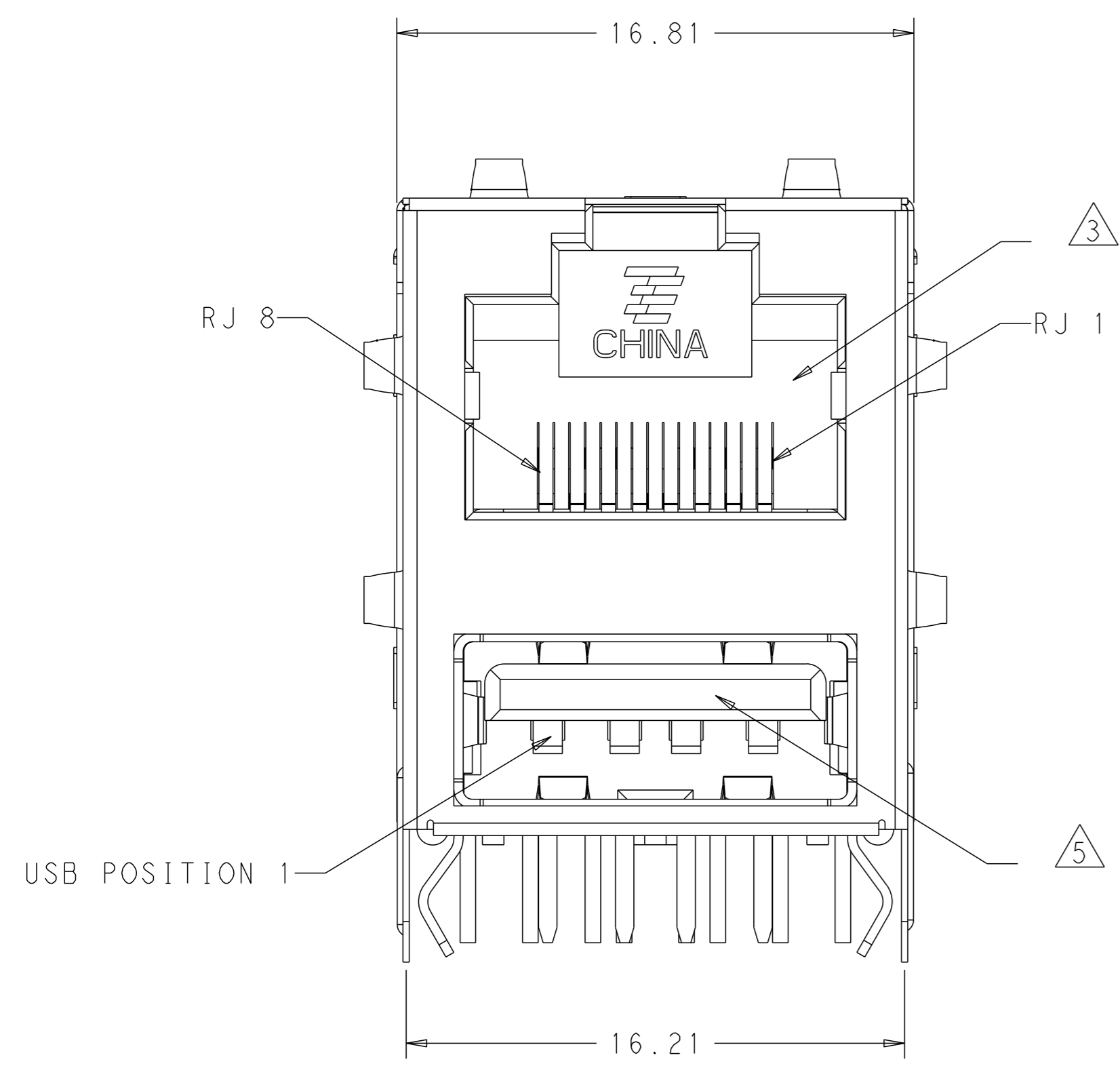
2. OPERATING TEMPERATURE -40°C TO +85°C.

3. RJ45 CAVITY CONFORMS TO FCC RULES AND REGULATION PART 68 SUBPART F.

4. TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY LOGO TO BE MARKED IN APPROXIMATE LOCATION SHOWN.

5. MATING INTERFACE COMPLIES WITH USB SPECIFICATION REV 2.0.

6. THESE PARTS ARE RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.



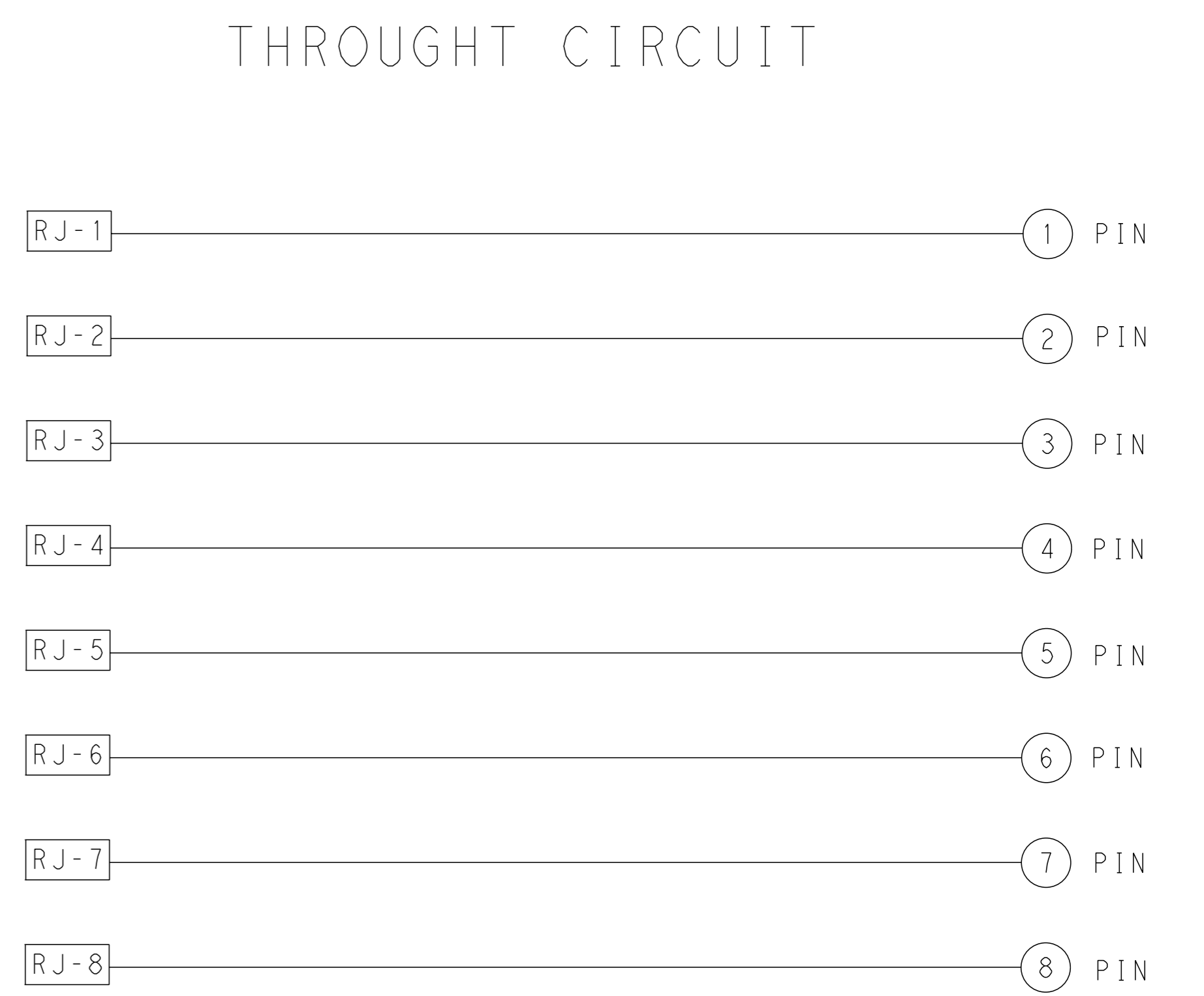
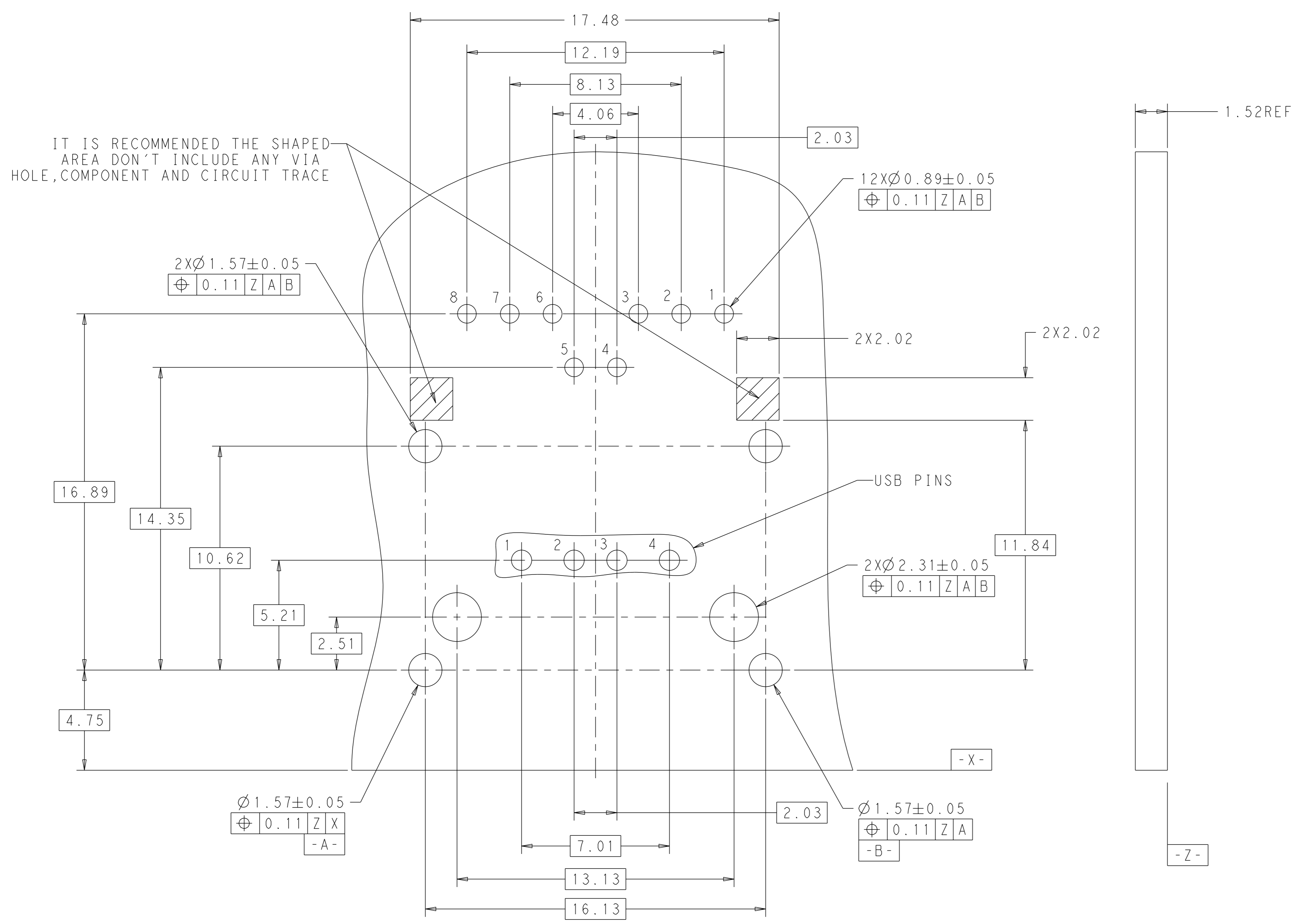
OBSELETE	3.81	3.81	1840035-2
	3.18	3.18	1840035-1
	DIM B	DIM A	PART NO.

THIS DRAWING IS A CONTROLLED DOCUMENT.

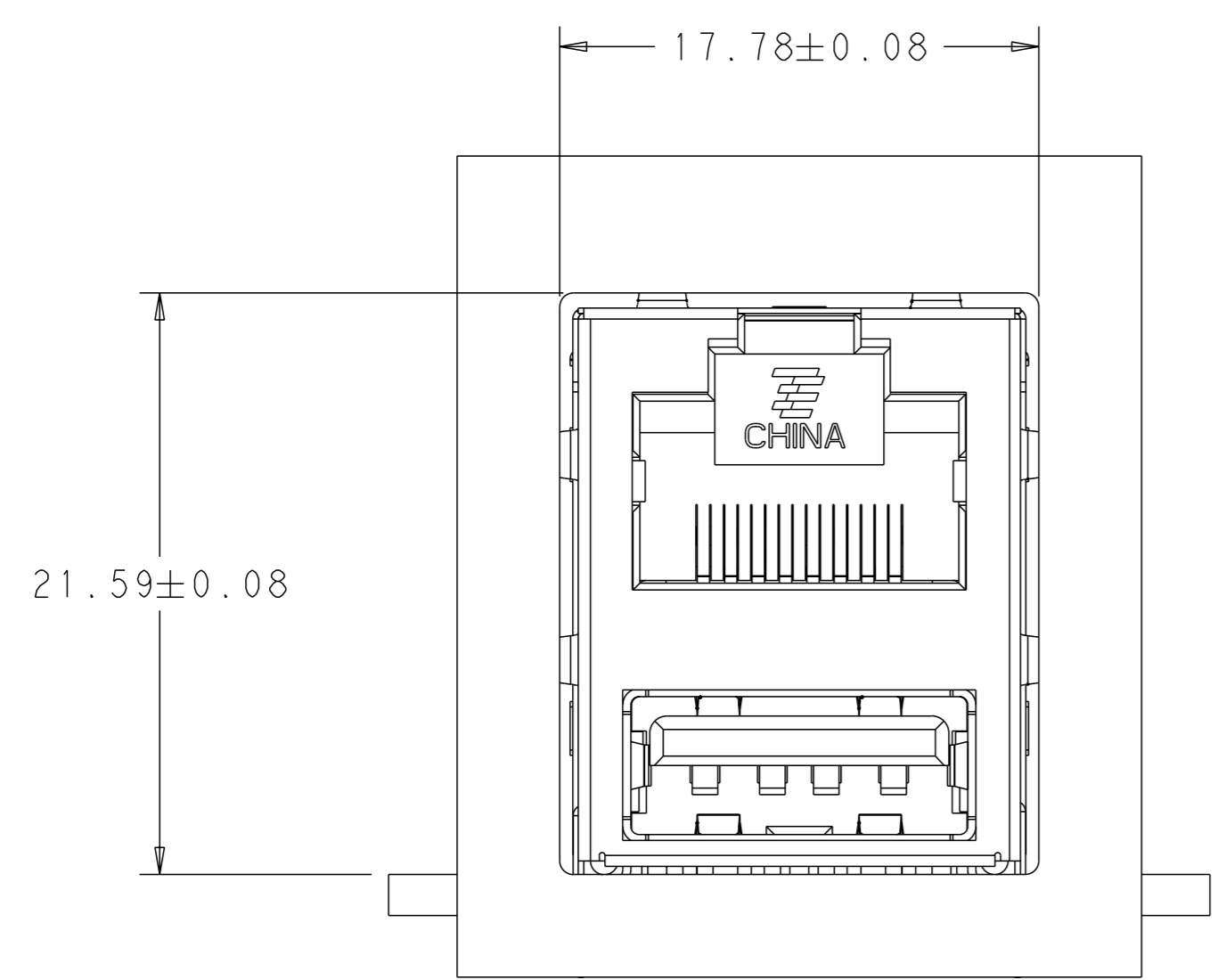
DIMENSIONS:	TOLERANCES UNLESS OTHERWISE SPECIFIED:	OWN: WILLIAM/COLIN 08DEC2010	CHK: TOWER YU 08DEC2010	APVD: KEITH ZHU 08DEC2010	NAME: RJ45(TM) OVER SINGLE USB THROUGH CIRCUIT, W/O LEDS
mm	0 PLC ± 1 PLC ± 2 PLC ±0.25 3 PLC ±0.25 4 PLC ± ANGLES ±*	SIZE: A1	CAGE CODE: 100779	DRAWING NO: 1840035	RESTRICTED TO: -
MATERIAL:	FINISH:	WEIGHT:	CUSTOMER DRAWING		SCALE: 5:1 SHEET 1 OF 2 REV C

STC TE Connectivity

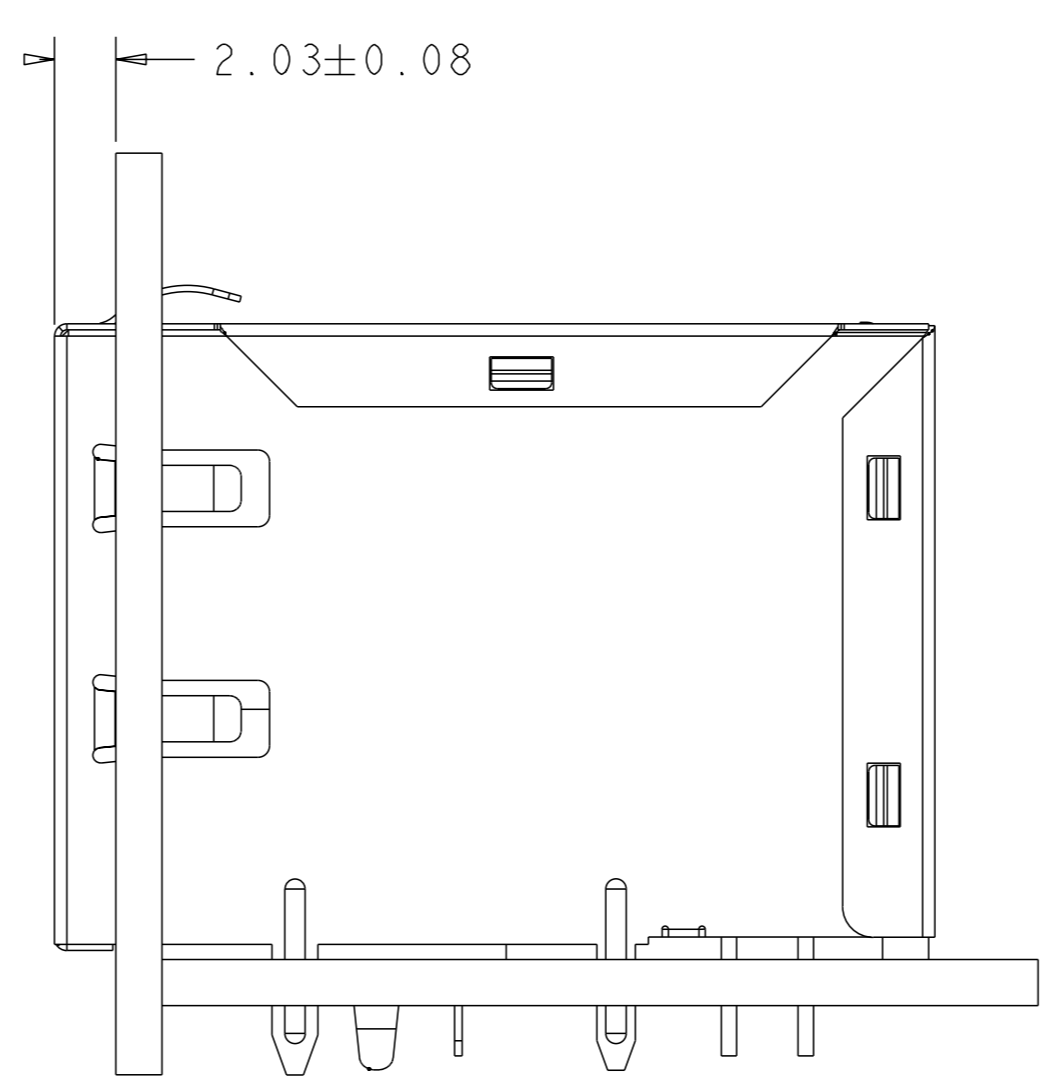
REVISIONS				
REV	DATE	DESCRIPTION	OWN	APPV
1		SEE SHEET 1		



RECOMMENDED PCB LAYOUT (TOL: ±0.10)  
COMPONENT SIDE



SUGGESTED PANEL CUT-OUT



THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN: WILLIAM/COLIN 08DEC2010	TE Connectivity
DIMENSIONS: mm		CHK: TOWER YU 08DEC2010	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD: KEITH ZHU 08DEC2010	NAME: RJ45(TM) OVER SINGLE USB THROUGH CIRCUIT, W/O LEDS
0 PLC ±	1 PLC ±	PRODUCT SPEC: 108-104005	SIZE: A1
2 PLC ±0.25	3 PLC ±0.25	APPLICATION SPEC:	CAGE CODE: 1840035
4 PLC ±	ANGLES ±	FINISH: *	RESTRICTED TO:
MATERIAL:	WEIGHT:	CUSTOMER DRAWING	SCALE: 5:1 SHEET 2 OF 2 REV C